

### **Amendment to Claims**

1-45 (canceled).

46 (original). A manufacturing method comprising forming one or more conductive contact pads in a first substrate, and forming dielectric over the one or more contact pads, with the dielectric having one or more openings which overlie the contact pads and also overlie one or more regions adjacent to the contact pads.

47 (original). The method of Claim 46 wherein the regions adjacent to the contact pads are less solder wettable than the contact pads.

48 (original). The method of Claim 46 wherein the regions adjacent to the contact pads are dielectric regions.

49 (original). The method of Claim 46 further comprising:

placing solder paste into the one or more openings; and

heating the solder paste to melt the solder.

50 (original). The method of Claim 49 further comprising soldering one or more contact pads of a second substrate to the one or more contact pads of the first substrate with solder obtained from the solder paste.

51 (original). The method of Claim 50 wherein the second substrate is a semiconductor integrated circuit.

52 (original). The method of Claim 46 wherein the first substrate is a semiconductor integrated circuit.

53 (original). The method of Claim 46 wherein the first substrate is an integrated circuit packaging substrate which does not include a semiconductor substrate.

54 (new). A manufacturing method comprising forming one or more conductive contact pads in a first substrate, the one or more conductive contact pads including a first

contact pad, and forming dielectric over the one or more contact pads, with the dielectric having one or more openings, the one or more openings comprising a first opening, wherein each of the contact pads occupies at least a portion of a bottom surface of at least one of the contact openings, wherein the first contact pad occupies a first portion of the bottom surface of the first contact opening but does not occupy a second portion of the bottom surface of the first contact opening.

55 (new). The method of Claim 54 wherein the second portion is less solder wettable than the first contact pad.

56 (new). The method of Claim 54 wherein the second portion is dielectric.

57 (new). The method of Claim 54 further comprising:

placing solder paste into the one or more openings; and

heating the solder paste to melt the solder.

58 (new). The method of Claim 57 further comprising soldering one or more contact pads of a second substrate to the one or more contact pads of the first substrate with solder obtained from the solder paste.

59 (new). The method of Claim 58 wherein the second substrate is a semiconductor integrated circuit.

60 (new). The method of Claim 54 wherein the first substrate is a semiconductor integrated circuit.

61 (new). The method of Claim 54 wherein the first substrate is an integrated circuit packaging substrate which does not include a semiconductor substrate.